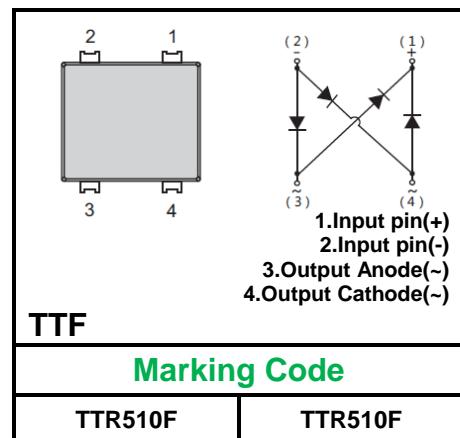


5A SURFACE MOUNT GLASS PASSIVATED BRIDGE
RECTIFIER Reverse Voltage - 100 to 1000 V
Forward Current – 5.0A
FEATURES

- ◆ High current capability
- ◆ Low forward voltage drop
- ◆ Glass Passivated Chip Junction
- ◆ Designed for Surface Mount Application
- ◆ Lead free in comply with EU RoHS 2011/65/EU directives


MECHANICAL DATA

- ◆ Case: TTF
- ◆ Terminals: Solderable per MIL-STD-750, Method 2026
- ◆ Approx. Weight: 0.461g / 0.0163oz

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	TTR510F	Units
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	1000	V
Maximum RMS voltage	V_{RMS}	700	V
Maximum DC Blocking Voltage	V_{DC}	1000	V
Average Rectified Output Current at $T_c=100^\circ\text{C}$	I_o	5.0	A
Peak Forward Surge Current 8.3 ms Single Half Sine-Wave Superimposed on Rated Load(JEDEC method)	I_{FSM}	180	A
I ² t Rating for Fusing	I^2t	134.46	A^2s
Typical Thermal Resistance (Note1)	$R_{\theta JA}$ $R_{\theta JC}$ $R_{\theta JL}$	60 10 12	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_j, T_{stg}	-55 ~ +150	$^\circ\text{C}$

(1) Mounted on glass epoxy PC board with 4x1.5" x 1.5" (3.81x3.81 cm) copper pad.

Maximum Ratings and Electrical characteristics

Ratings at 25 °C ambient temperature unless otherwise specified.

Parameter	Symbols	Test Conditions	Typ	Max	Units
Instantaneous forward voltage	V_F	$I = 5\text{A}$ $T_J = 25^\circ\text{C}$	-	1.0	V
Reverse current at DC blocking voltage	I_R	$T_J = 25^\circ\text{C}$ $T_J = 125^\circ\text{C}$	-	1 200	μA
Maximum Reverse Recovery Time	T_{rr}	Measured with $I_F = 0.5\text{A}$, $I_R = 1\text{A}$, $I_{rr} = 0.25 \text{ A}$.	-	500	nS
Typical Junction Capacitance	C_J	$f = 1\text{MHz}$, $V_R = 4\text{V DC}$ $T_J = 25^\circ\text{C}$	60	-	pF

Fig.1 Average Rectified Output Current Derating Curve

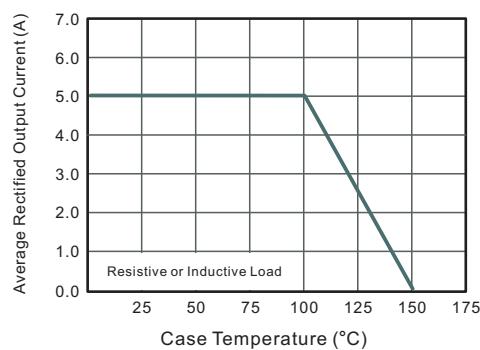


Fig.2 Typical Reverse Characteristics

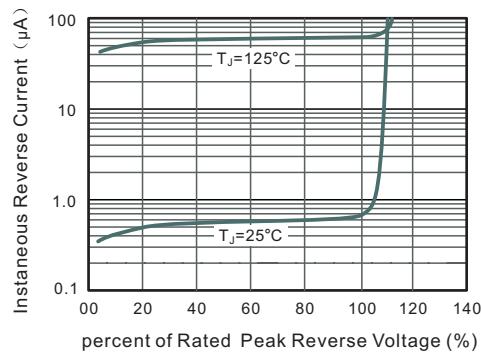


Fig.3 Typical Instantaneous Forward Characteristics

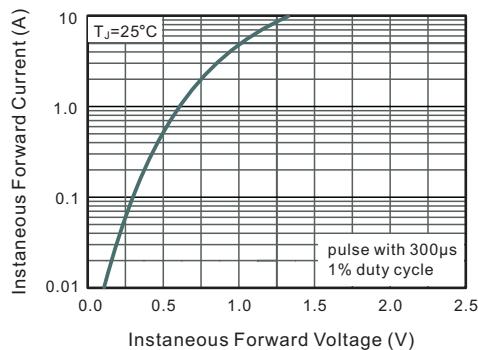


Fig.4 Typical Junction Capacitance

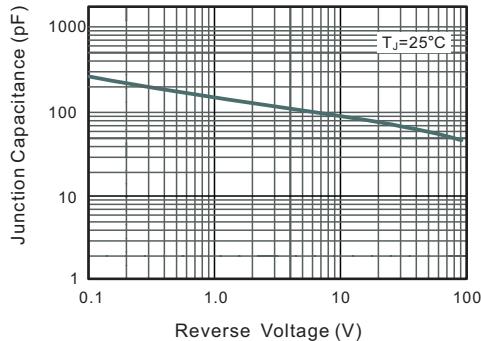


Fig.5 Maximum Non-Repetitive Peak Forward Surge Current

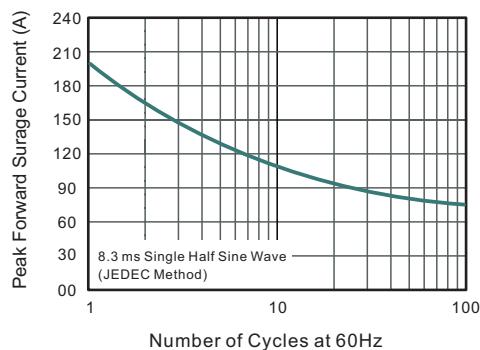
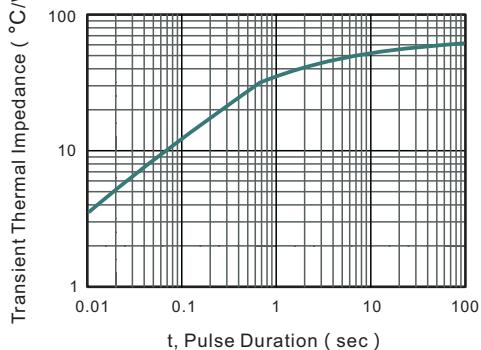


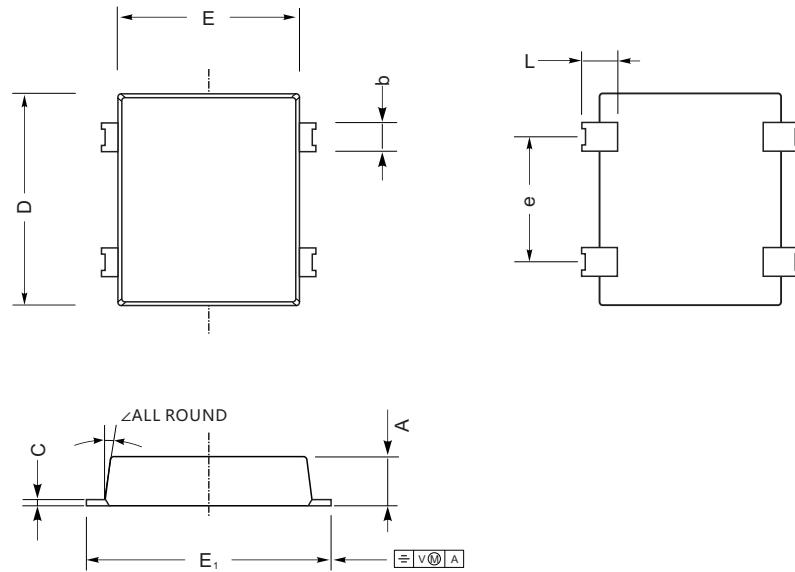
Fig.6- Typical Transient Thermal Impedance



Package Outline

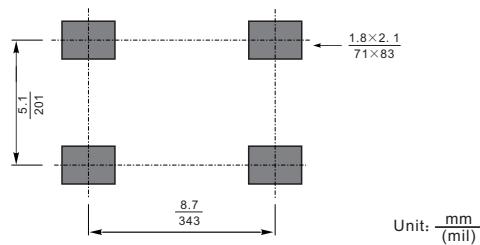
TTF

Plastic surface mounted package; 4leads



UNIT		A	C	D	E	E ₁	L	e	b	∠
mm	max	1.75	0.55	9.8	8.8	10.2	1.25	5.3	1.55	10°
	min	1.35	0.25	9.4	8.4	9.8	0.85	4.9	1.25	
mil	max	68	21.6	385	346	401	49	209	61	10°
	min	53	9.8	370	330	385	33	193	49	

The recommended mounting pad size



Summary of Packing Options

Package	Packing Description	Packing Quantity	Industry Standard
TTF	Tape/Reel,13"reel	3000	EIA-481-1